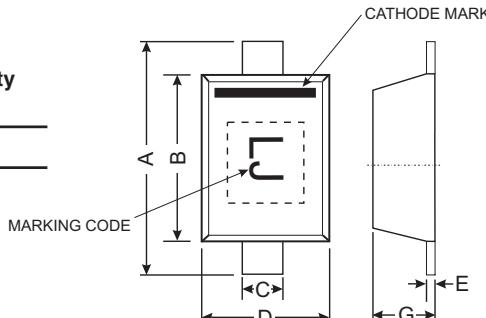


Features

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- Lead Free By Design/RoHS Compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device, Note 4 and 5

Mechanical Data

- Case: SOD-523
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish - Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Code: LJ
- Ordering Information: See Last Page
- Weight: 0.002 grams (approximate)



SOD-523		
Dim	Min	Max
A	1.50	1.70
B	1.10	1.30
C	0.25	0.35
D	0.70	0.90
E	0.10	0.20
G	0.55	0.65

All Dimensions in mm

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum Peak Reverse Voltage	V_{RM}	45	V
Reverse Voltage	V_R	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Average Forward Current	I_0	100	mA
Maximum (Peak) Forward Current	I_{FM}	300	mA
Non-Repetitive Peak Forward Surge Current @ $t \leq 10\text{ms}$	I_{FSM}	1	A
Operating and Storage Temperature Range	T_j, T_{STG}	-40 to +125	°C

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

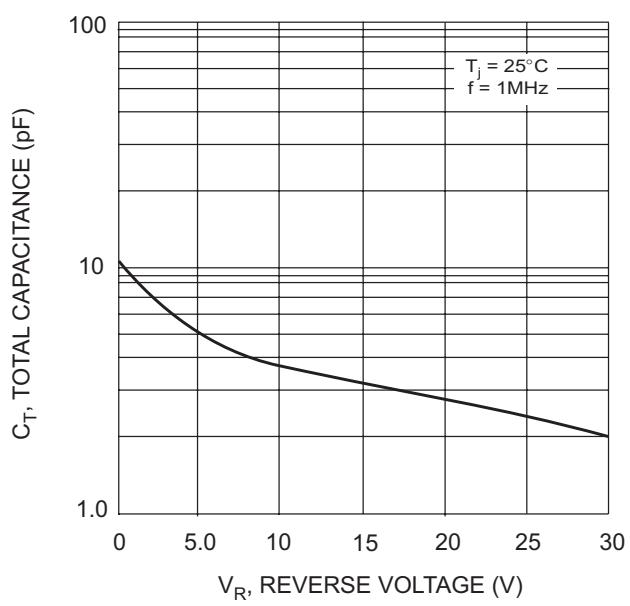
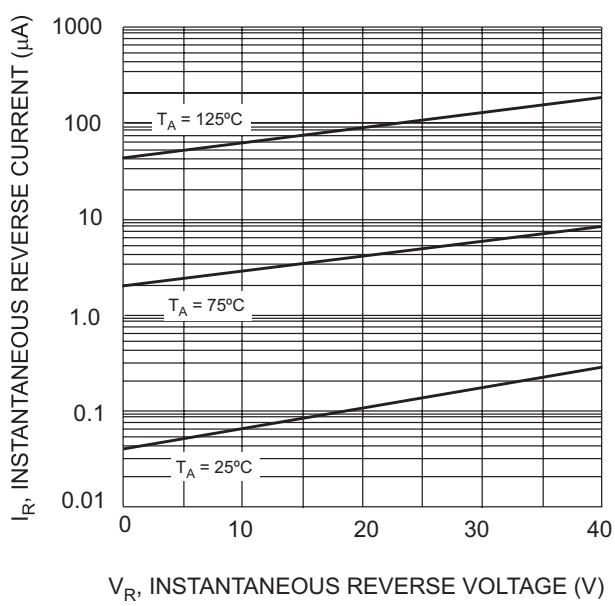
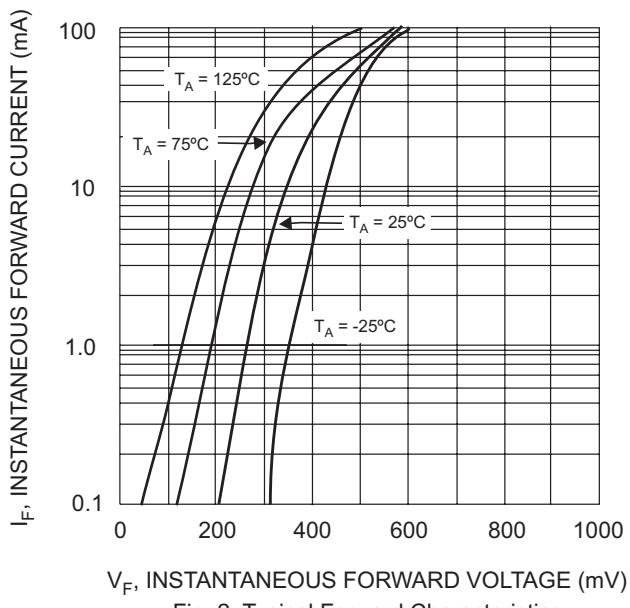
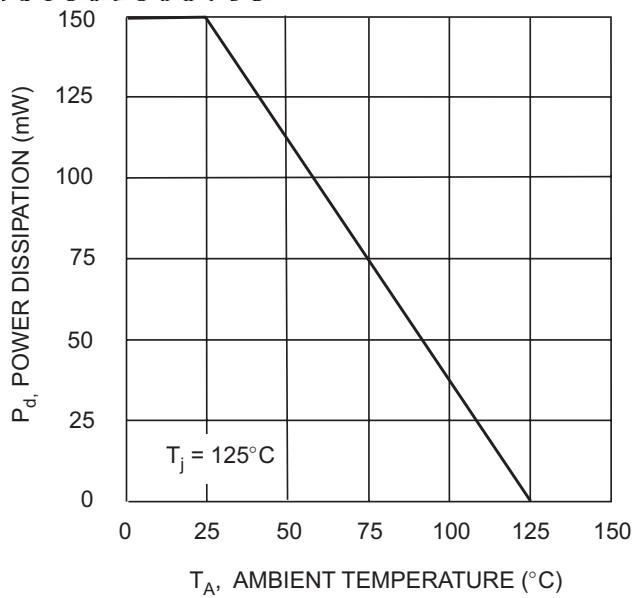
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_d	150	mW
Thermal Resistance, Ambient Air (Note 2)	$R_{\theta JA}$	667	°C/W

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 3)	$V_{(BR)R}$	30	—	—	V	$I_F = 100\mu\text{A}$
Forward Voltage Drop	V_F	—	280 360 470 580	— — 550 800	mV	$I_F = 1.0\text{mA}$ $I_F = 15\text{mA}$ $I_F = 50\text{mA}$ $I_F = 100\text{mA}$
Reverse Current (Note 3)	I_R	—	—	1.0	μA	$V_R = 25\text{V}$
Total Capacitance	C_T	—	4	15	pF	$V_R = 10\text{V}$, $f = 1.0\text{ MHz}$

Note:

1. No purposefully added lead.
2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
3. Short duration pulse test used so as to minimize self-heating effect.
4. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
5. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.


Ordering Information (Note 5 & 6)

Device	Packaging	Shipping
SDM10U45-7	SOD-523	3000/Tape & Reel

Note: 5. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 6. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

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